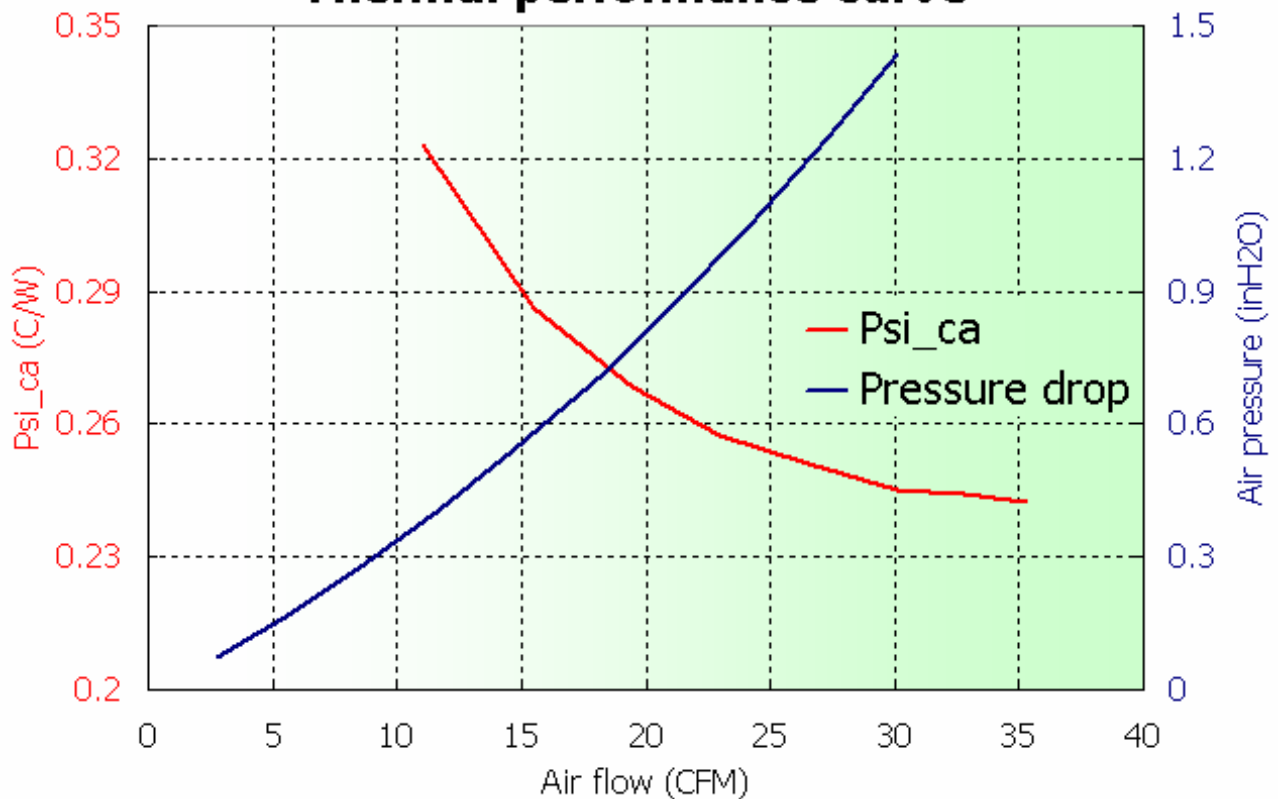


1. Application : AMD G34 Socket 1U Passive HSK
2. Material : Cu 1100 (BASE) + Cu 1100 / Al 1100 (FIN)
3. Weight : 455g
4. Type : Soldering
5. Dimension : 116.24*74.0*27.0 [mm³]
6. Heat source size : 37.5*37.5 [mm²]
(AM2 TTV)
7. Thermal Interface Material :
SHIN ETSU X23-7762
8. Test Condition : Fully Ducted



Thermal performance curve



* All readings are typical values at rated voltage.
* Specifications are subject to change without notice

